

General statement on RoHS/China RoHS

Date: Mai 2023

Dear Customers.

the following statement applies to all unassembled printed circuit boards produced by the KSG Group.

In accordance with EU Directive 2011/65/EU and amendments 2015/863/EU and 2017/2102/EU, the following restricted materials are <u>not</u> used in our products above the compulsory weight limit:

- Mercury (0.1%)
- Lead (0.1%)
- Cadmium (0.01%)
- Hexavalent chromium (0.1%)
- Polybrominated biphenyls (PBB) (0.1%)
- Polybrominated diphenyl ethers (PBDE) (e.g. pentaBDE and octaBDE) (0.1%)
- Phthalates DEHP, BBP, DBP, DIBP (0.1%)

A restriction applies to the use of lead where printed circuit boards are explicitly ordered with a leaded HAL (hot air levelling) solder surface. The end product only conforms to EU Directive 2011/65/EU if you have a valid exemption for the end product. Of course, we have RoHS-compliant solder surfaces available in-house as an alternative.

This statement also applies in respect of China-RoHS 2 and Directive 2012/19/EU (WEEE).

KSG regularly monitors the above directives for updates and amends its declarations as necessary.

Please do not hesitate to contact us if you have any further questions.

KSG Group

In representation of Holger Bönitz Head of Central Quality Management

On behalf of Gunter Laubert Environmental Management Officer Gornsdorf Site